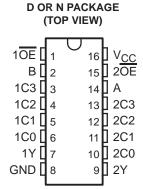
### SN74AS353B DUAL 1-OF-4 DATA SELECTOR/MULTIPLEXER WITH 3-STATE OUTPUTS

SDAS222A - APRIL 1982 - REVISED DECEMBER 1994

- Inverting Version of 'AS253
- Permits Multiplexing From n Lines to One Line
- Performs Parallel-to-Serial Conversion
- Package Options Include Plastic Small-Outline (D) Packages and Standard Plastic (N) 300-mil DIPs

### description

This data selector/multiplexer contains inverters and drivers to supply full binary decoding data selection to the AND-OR-invert gates. Separate output-enable (OE) inputs are provided for each of the two 4-line sections.



The 3-state outputs can interface with and drive data lines of bus-organized systems. With all but one of the common outputs disabled (at the high-impedance state), the low impedance of the single enabled output drives the bus line to a high or low logic level. Each section has its own output enable. The output is disabled when  $\overline{\text{OE}}$  is high.

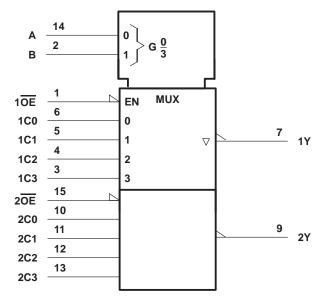
The SN74ALS353B is characterized for operation from 0°C to 70°C.

**FUNCTION TABLE** 

	OLITPUT.							
SEL	ECT	DATA				OE	OUTPUT	
В	Α	C0	C1	C2	C3	OE	·	
Х	Χ	Χ	X	Х	X	Н	Z	
L	L	L	X	X	X	L	Н	
L	L	Н	Χ	X	Χ	L	L	
L	Н	Χ	L	X	X	L	Н	
L	Н	Χ	Н	X	Χ	L	L	
Н	L	Χ	Χ	L	Χ	L	Н	
Н	L	Χ	Χ	Н	Χ	L	L	
Н	Н	Х	Χ	Χ	L	L	Н	
Н	Н	Х	Χ	Χ	Н	L	L	

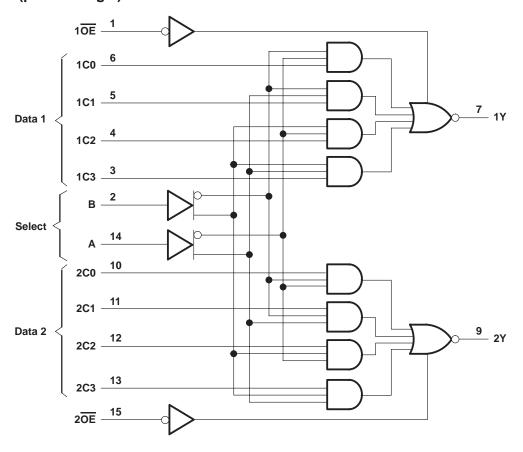
Select inputs A and B are common to both sections.

### logic symbol†



<sup>†</sup> This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

### logic diagram (positive logic)





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### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V <sub>CC</sub>		. 7 V
Input voltage, V <sub>I</sub>		. 7 V
Voltage applied to a disabled 3-state output		5.5 V
Operating free-air temperature range, T <sub>A</sub>	. 0°C to	70°C
Storage temperature range	65°C to	150°C

### recommended operating conditions

		MIN	NOM	MAX	UNIT
Vcc	Supply voltage	4.5	5	5.5	V
VIH	High-level input voltage	2			V
V <sub>IL</sub>	Low-level input voltage			8.0	V
IOH	High-level output current			-15	mA
lOL	Low-level output current			48	mA
TA	Operating free-air temperature	0		70	°C

# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER VIK		TEST COND	MIN	TYP‡	MAX	UNIT	
		V <sub>CC</sub> = 4.5 V,	I <sub>I</sub> = –18 mA			-1.2	V
VOН		V <sub>CC</sub> = 4.5 V to 5.5 V,	$I_{OH} = -2 \text{ mA}$	V <sub>CC</sub> -2			
		V <sub>CC</sub> = 4.5 V,	I <sub>OH</sub> = –15 mA	2.4	3.3		V
VOL		V <sub>CC</sub> = 4.5 V,	I <sub>OL</sub> = 48 mA		0.35	0.5	V
lozh		V <sub>CC</sub> = 5.5 V,	V <sub>O</sub> = 2.7 V			50	μΑ
lozL		V <sub>CC</sub> = 5.5 V,	V <sub>O</sub> = 0.4 V			-50	μΑ
	A, B					0.2	
Ц	All others	$V_{CC} = 5.5 V,$	V <sub>I</sub> = 7 V			0.1	mA
	A, B		V 07V			40	
lН	All others	$V_{CC} = 5.5 V,$	V <sub>I</sub> = 2.7 V			20	μΑ
	A, B					-1	
IIL	All others	$V_{CC} = 5.5 V,$	$V_{I} = 0.4 V$			-0.5	mA
ΙΟ§		V <sub>CC</sub> = 5.5 V,	V <sub>O</sub> = 2.25 V	-30		-112	mA
			Outputs high		15	24	
ICC		$V_{CC} = 5.5 V$	Outputs low	19		31	mA
			Outputs disabled		18	30	

<sup>‡</sup> All typical values are at  $V_{CC} = 5 \text{ V}$ ,  $T_A = 25^{\circ}\text{C}$ .



<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

<sup>§</sup> The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, IOS.

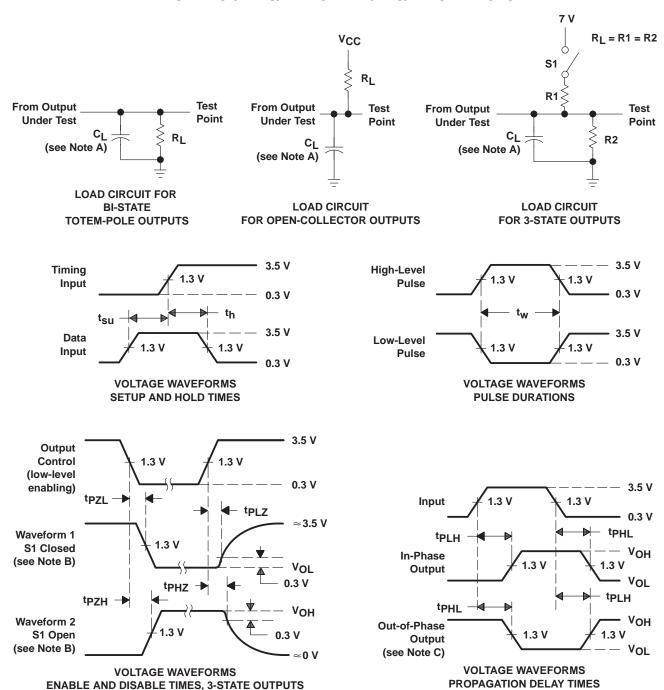
# **SN74AS353B** DUAL 1-OF-4 DATA SELECTOR/MULTIPLEXER WITH 3-STATE OUTPUTS SDAS222A - APRIL 1982 - REVISED DECEMBER 1994

## switching characteristics (see Figure 1)

PARAMETER	PARAMETER FROM (INPUT)		$\label{eq:CC} \begin{array}{l} \text{V}_{\text{CC}} = 4.5 \text{ V to } 5.5 \text{ V}, \\ \text{C}_{\text{L}} = 50 \text{ pF}, \\ \text{R1} = 500 \ \Omega, \\ \text{R2} = 500 \ \Omega, \\ \text{T}_{\text{A}} = \text{MIN to MAX}^{\dagger} \\ \hline \text{MIN} \qquad \text{MAX} \end{array}$		UNIT
tPLH t	A or B	Y	3	10	ns
<sup>t</sup> PHL	700	•	2.5	9	
<sup>t</sup> PLH	Data	Υ	2	7	ns
<sup>t</sup> PHL	(any C)	Y	1	6	
<sup>t</sup> PZH	ŌĒ	Υ	1	5	ns ns
<sup>t</sup> PZL	OE	Y	2	9	
<sup>t</sup> PHZ	ŌĒ	Υ	1	6	
t <sub>PLZ</sub>	OE .	ſ	1	5	

<sup>†</sup> For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

#### PARAMETER MEASUREMENT INFORMATION SERIES 54ALS/74ALS AND 54AS/74AS DEVICES



NOTES: A. C<sub>L</sub> includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. When measuring propagation delay items of 3-state outputs, switch S1 is open.
- D. All input pulses have the following characteristics: PRR  $\leq$  1 MHz,  $t_r = t_f = 2$  ns, duty cycle = 50%.
- E. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuits and Voltage Waveforms





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#### PACKAGE OPTION ADDENDUM

18-Sep-2008

#### **PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
SN74AS353BD	OBSOLETE	SOIC	D	16	TBD	Call TI	Call TI
SN74AS353BDR	OBSOLETE	SOIC	D	16	TBD	Call TI	Call TI
SN74AS353BN	OBSOLETE	PDIP	N	16	TBD	Call TI	Call TI

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

**Pb-Free** (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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## N (R-PDIP-T\*\*)

### PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



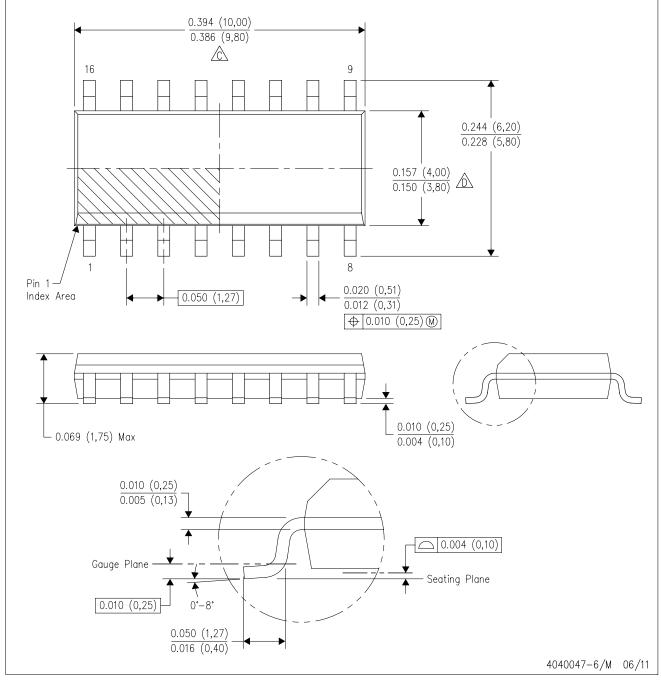
NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



## D (R-PDS0-G16)

### PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AC.



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